

Fig. 1A PRIOR ART

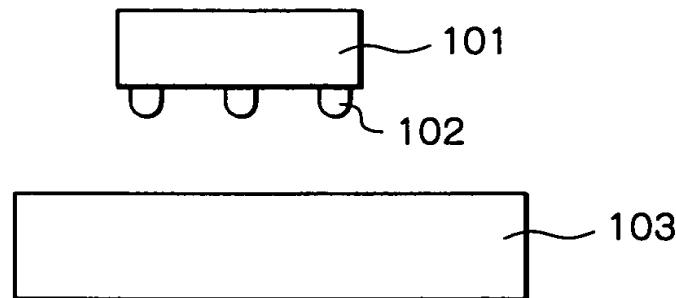


Fig. 1B PRIOR ART

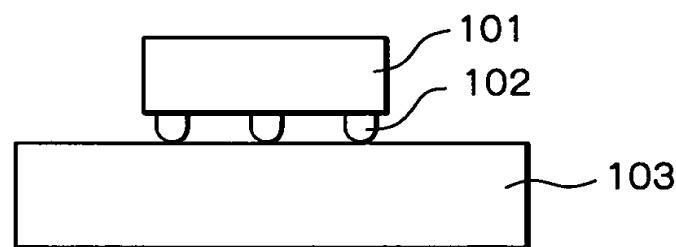
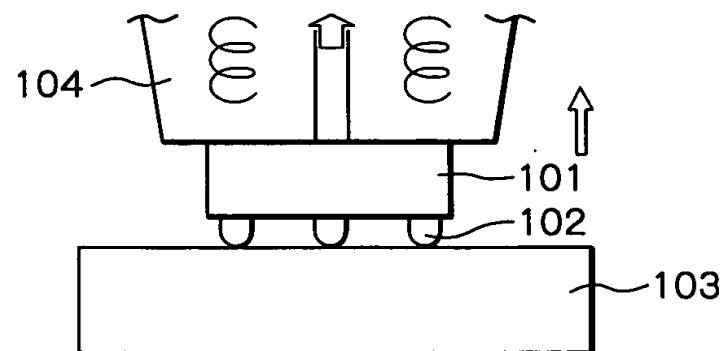


Fig. 1C PRIOR ART



Title: METHOD OF MANUFACTURING A
FLIP-CHIP SEMICONDUCTOR DEVICE
WITH A STRESS-ABSORBING LAYER
MADE OF THERMOSETTING RESIN
Inventor(s): Hirokazu HONDA
DOCKET NO.: 067123-0195

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Fig. 2A

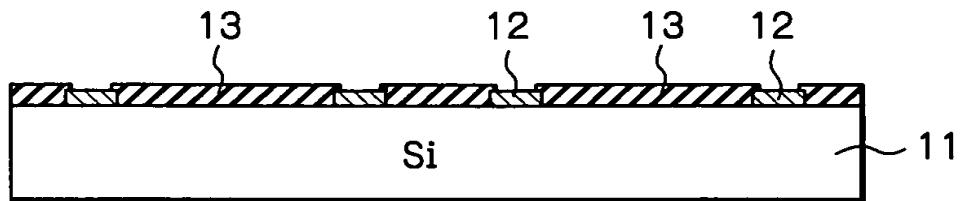


Fig. 2B

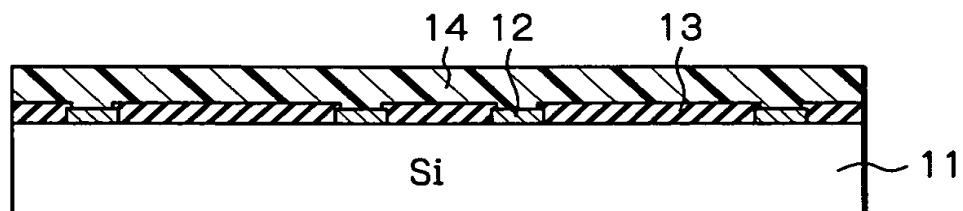


Fig. 2C

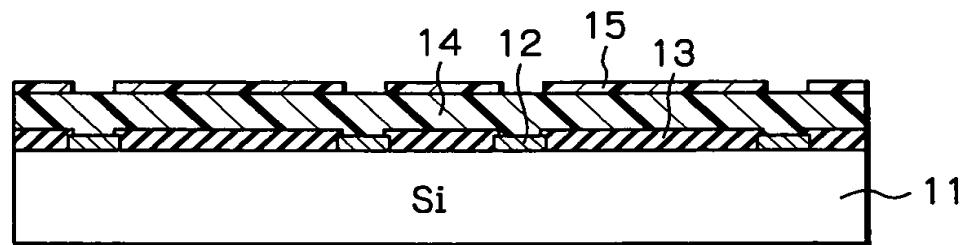


Fig. 2D

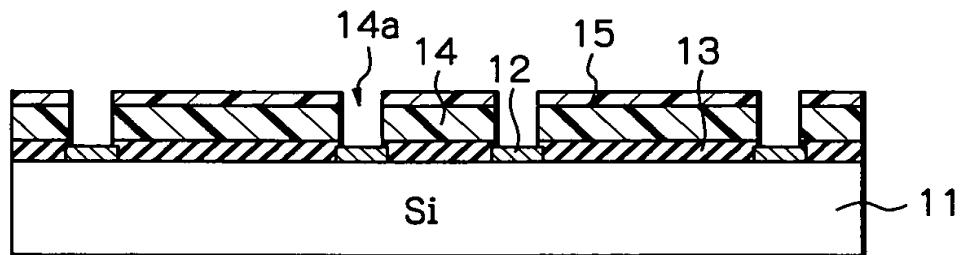


Fig. 2E

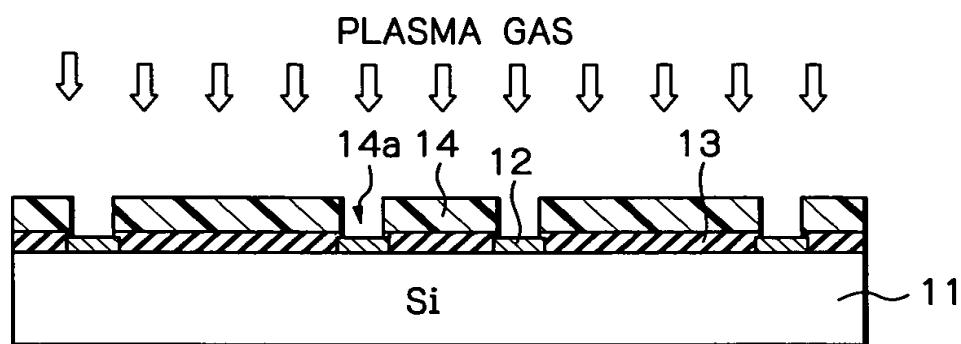
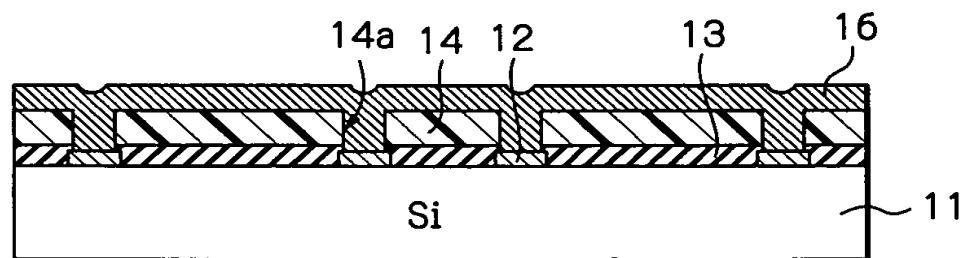


Fig. 2F



Title: METHOD OF MANUFACTURING A
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Fig. 2G

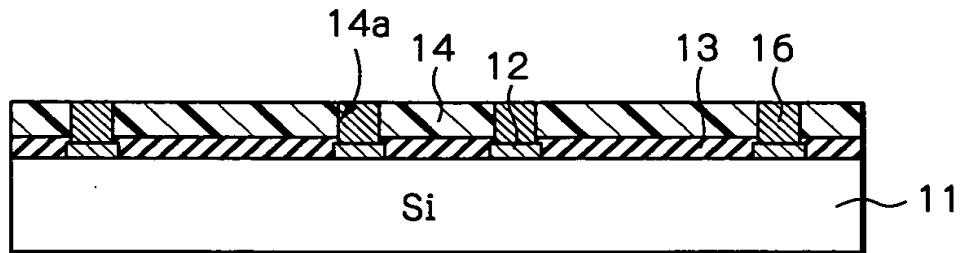


Fig. 2H

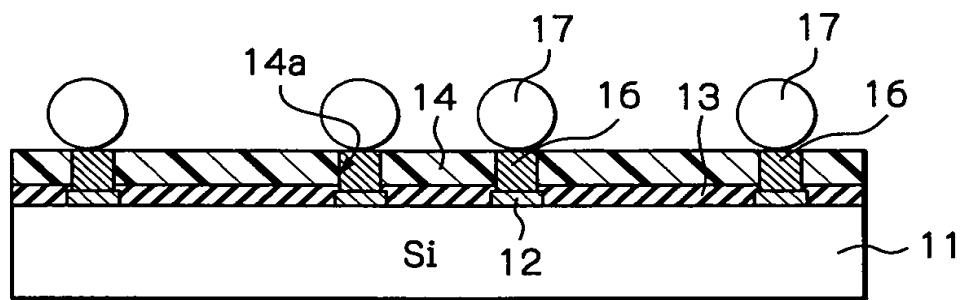
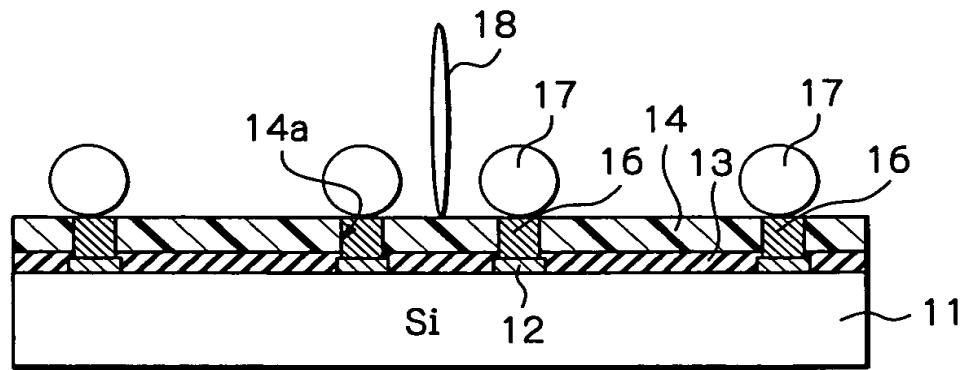


Fig. 2I

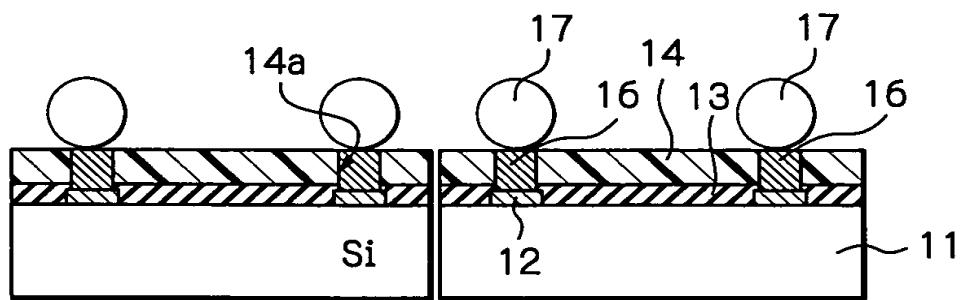


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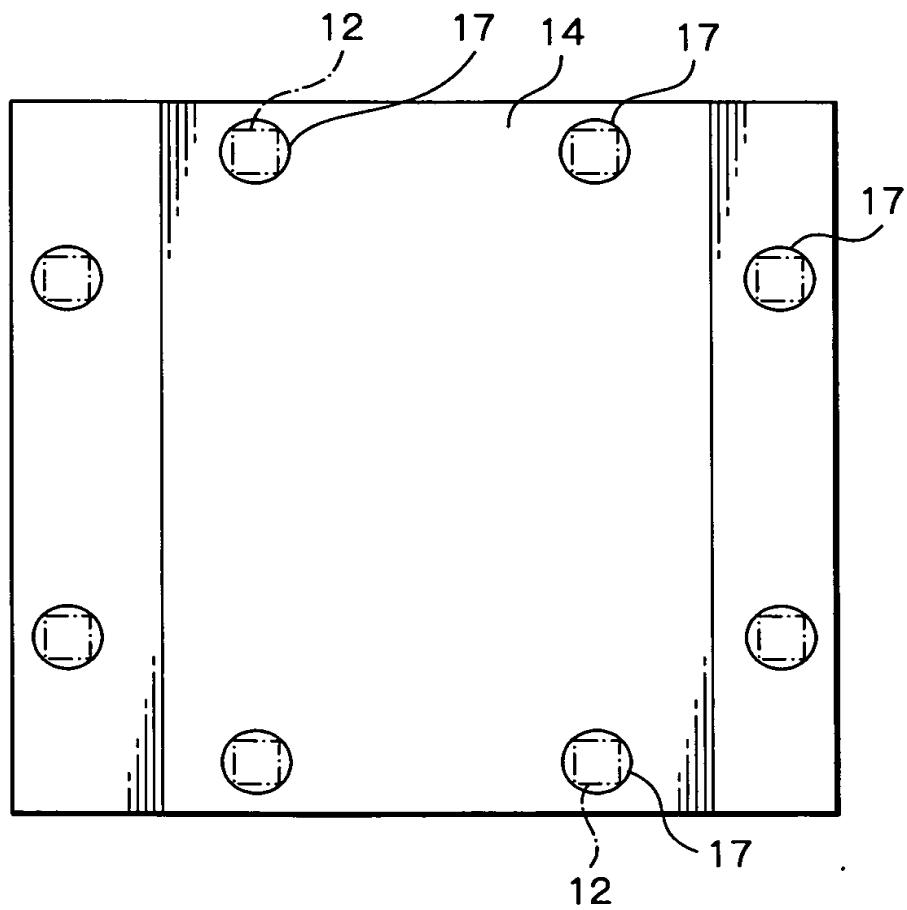
Fig. 2J



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Fig. 3

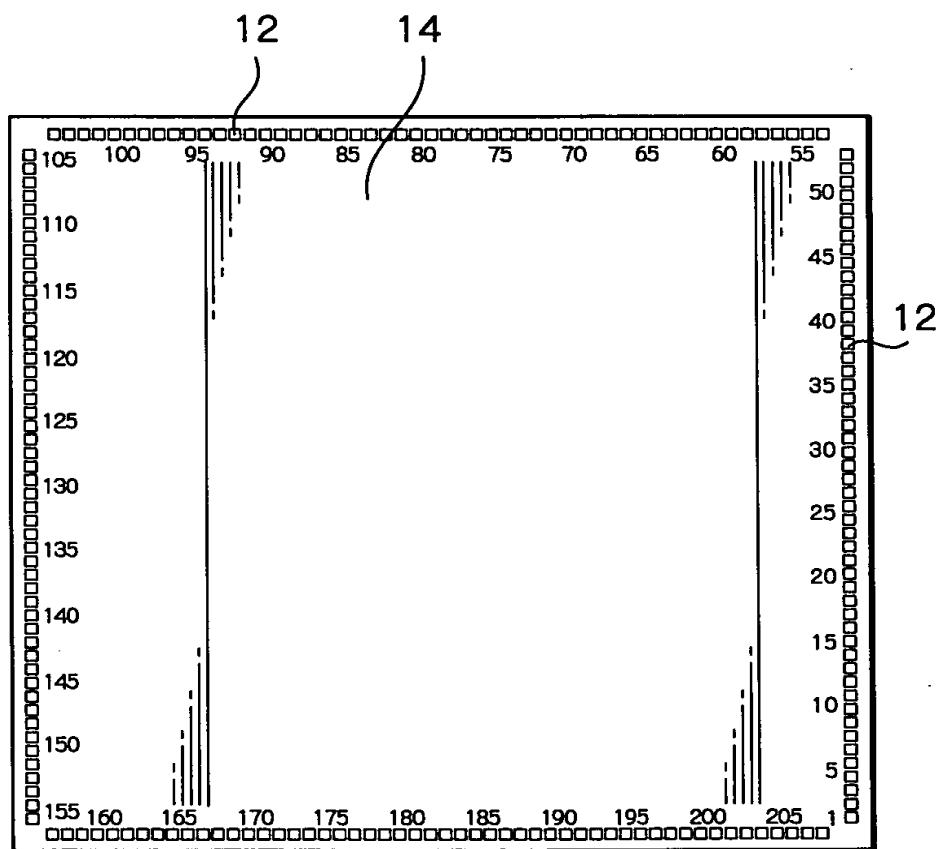


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Fig. 4



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Fig. 5A

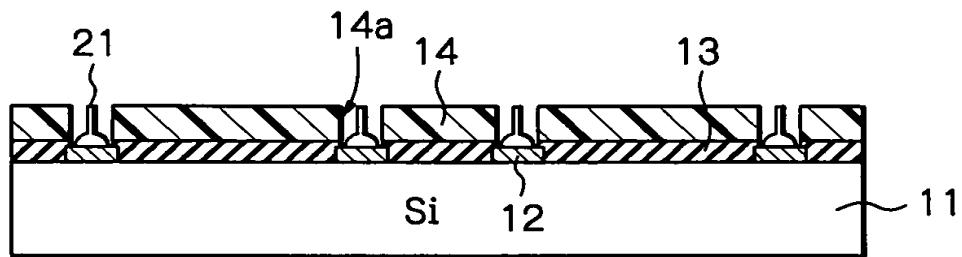


Fig. 5B

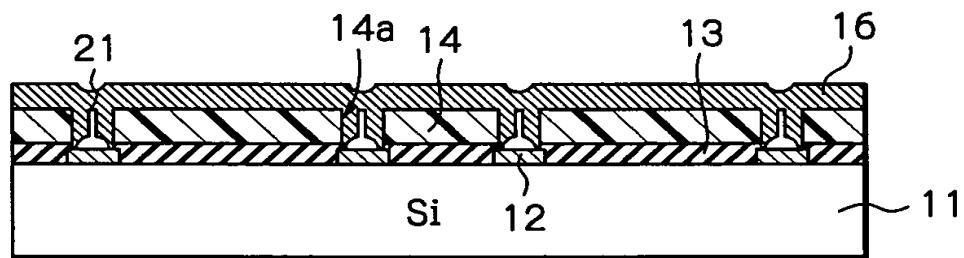
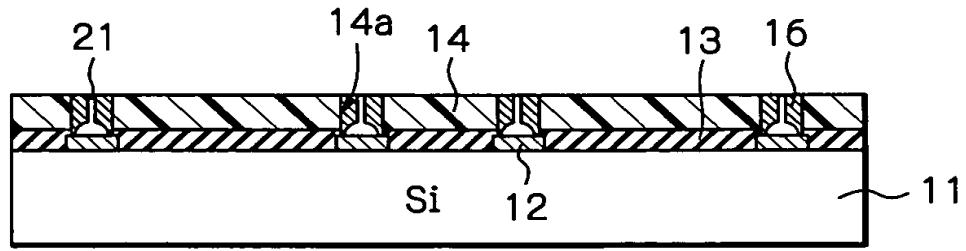


Fig. 5C



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Fig. 5D

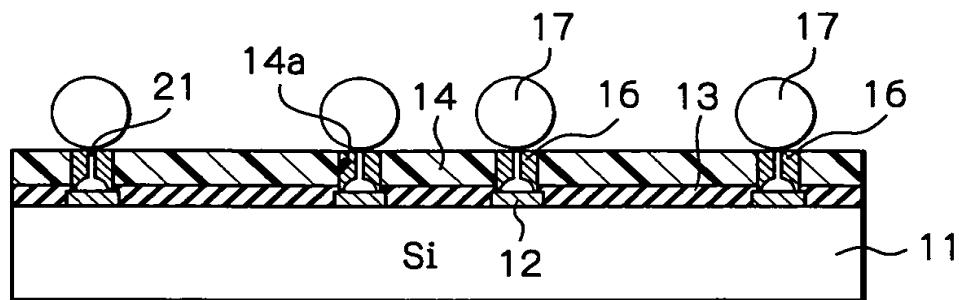


Fig. 5E

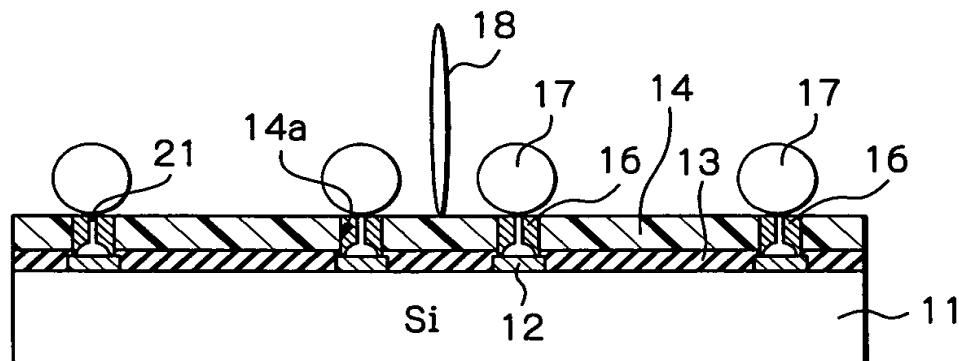


Fig. 5F

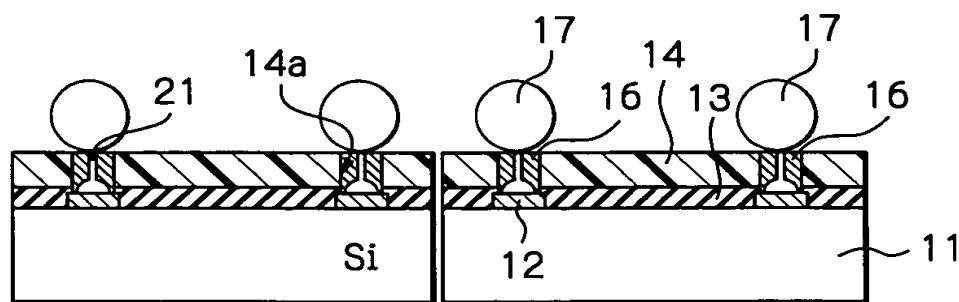


Fig. 6A

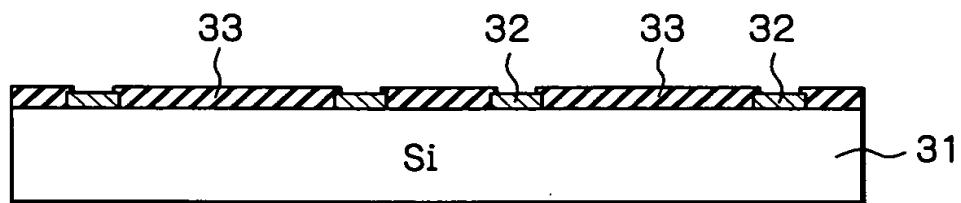


Fig. 6B

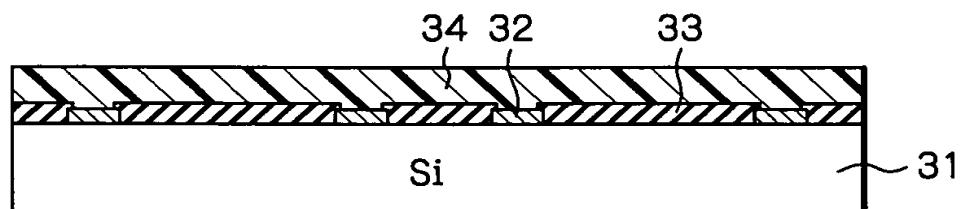


Fig. 6C

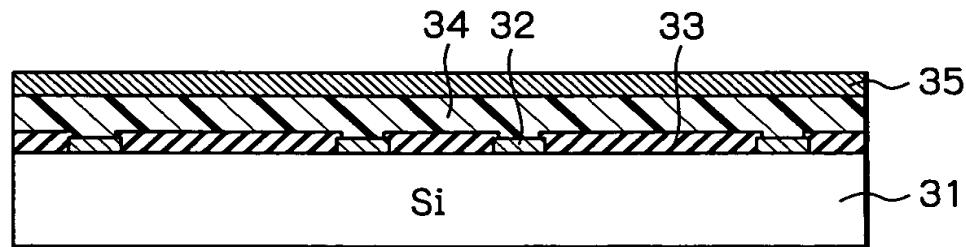


Fig. 6D

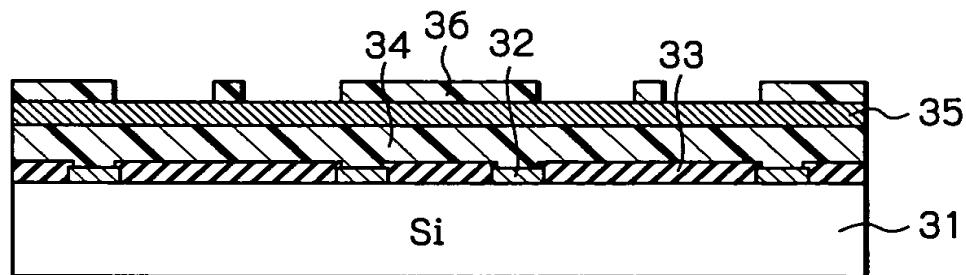


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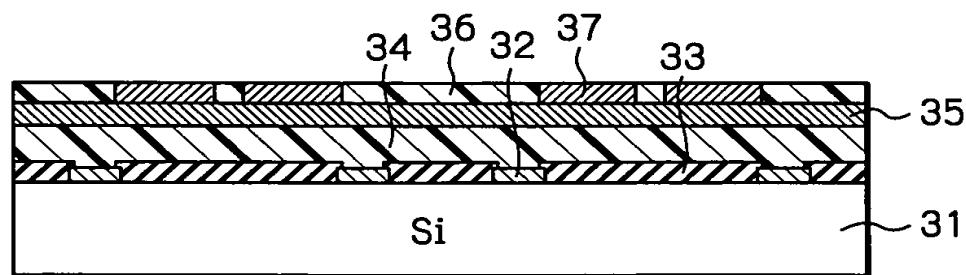
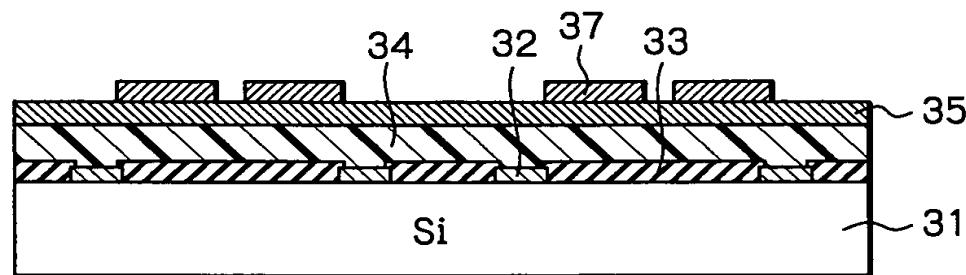


Fig. 6F



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Fig. 6G

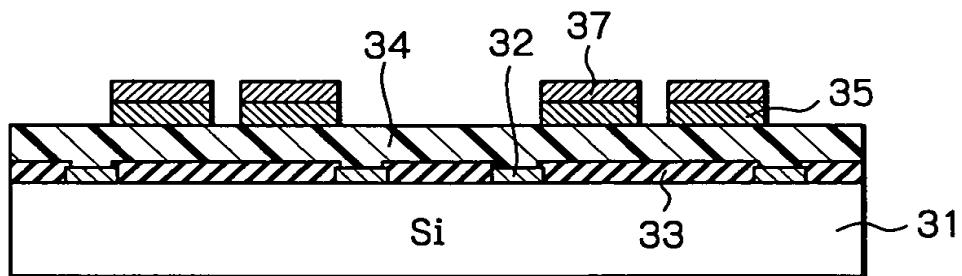


Fig. 6H

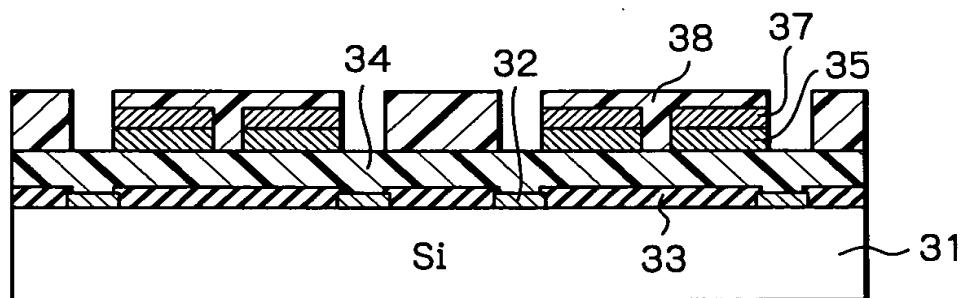
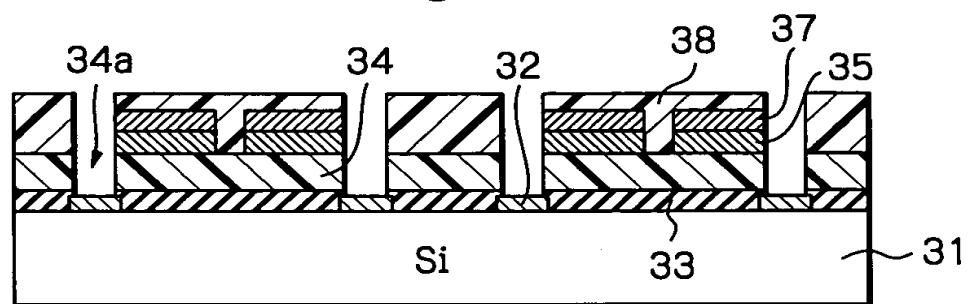


Fig. 6I



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Fig. 6J

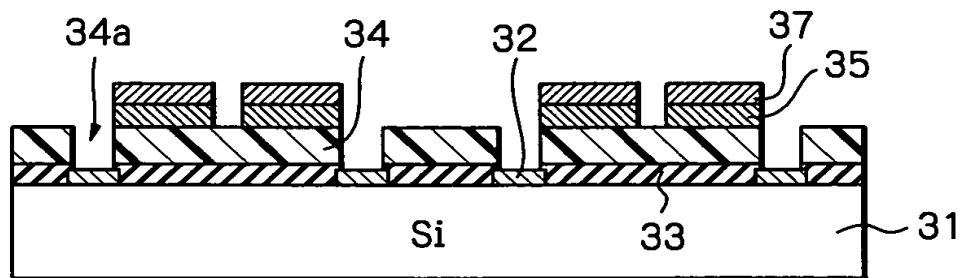


Fig. 6K

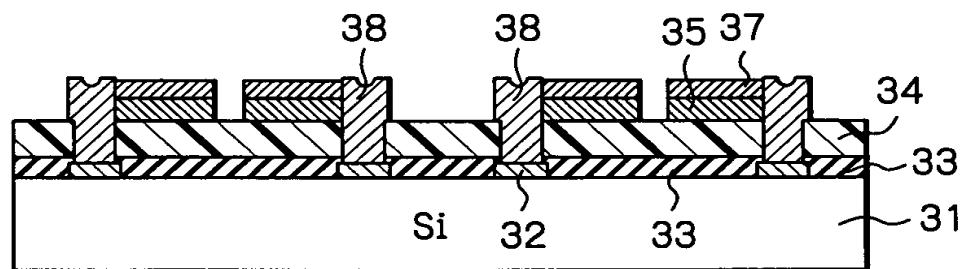
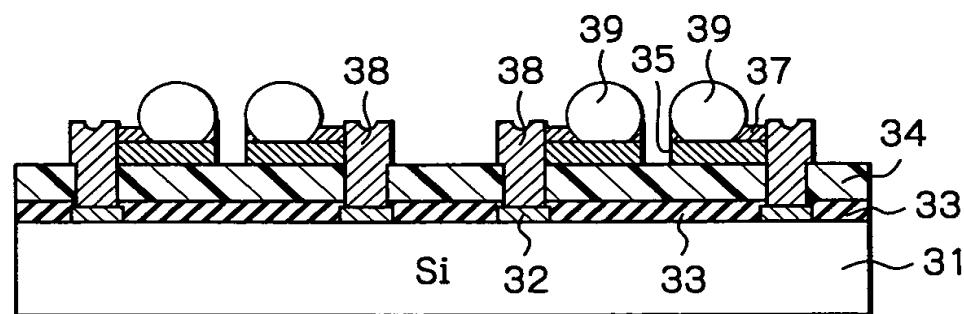


Fig. 6L



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Fig. 6M

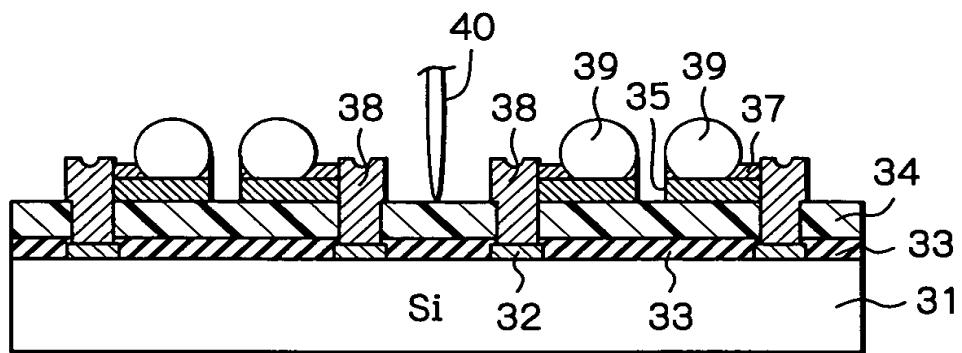
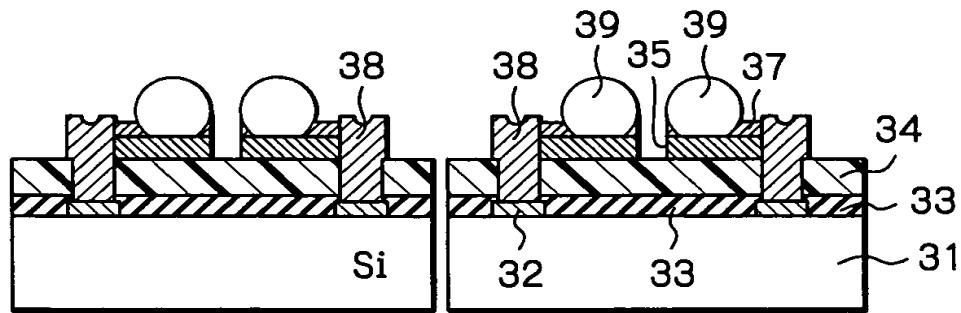


Fig. 6N

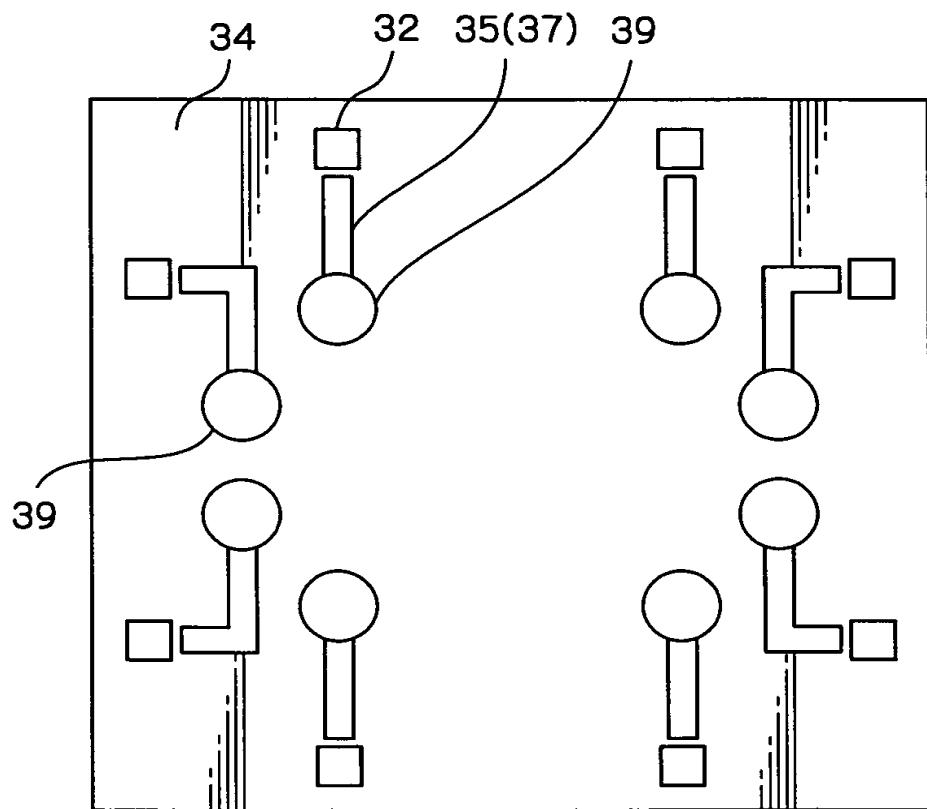


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Fig. 7



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Fig. 8A

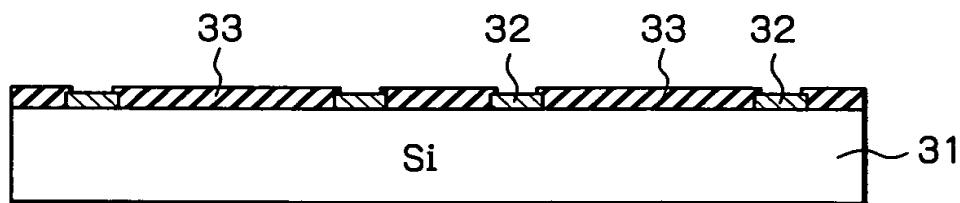


Fig. 8B

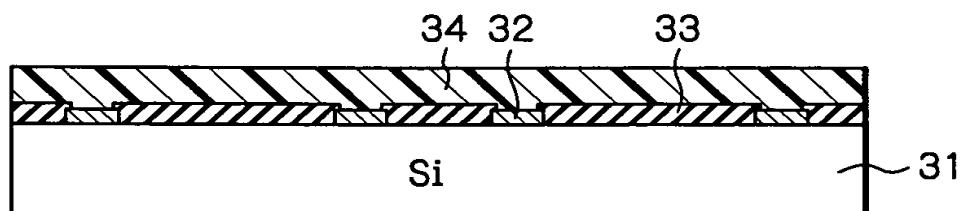
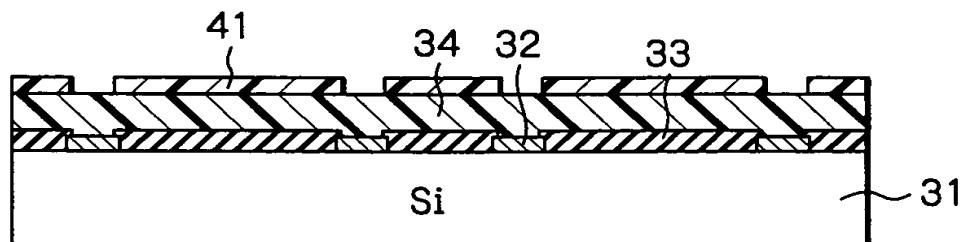


Fig. 8C



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Fig. 8D

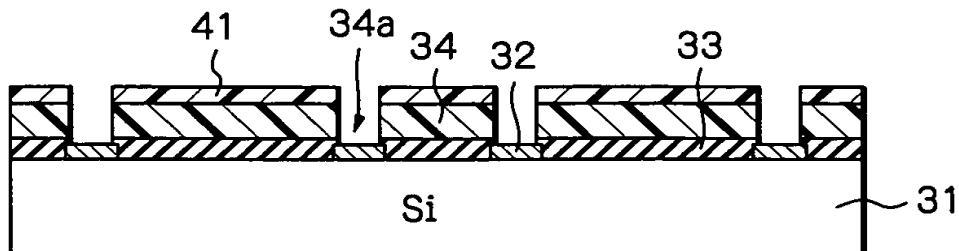


Fig. 8E

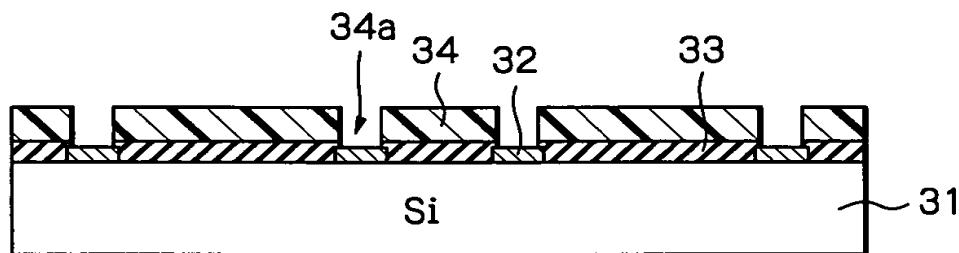


Fig. 8F

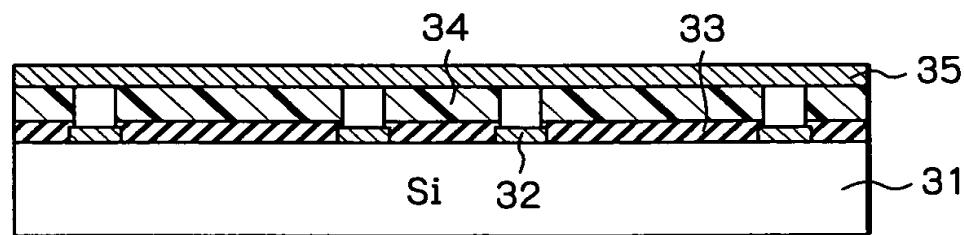


Fig. 8G

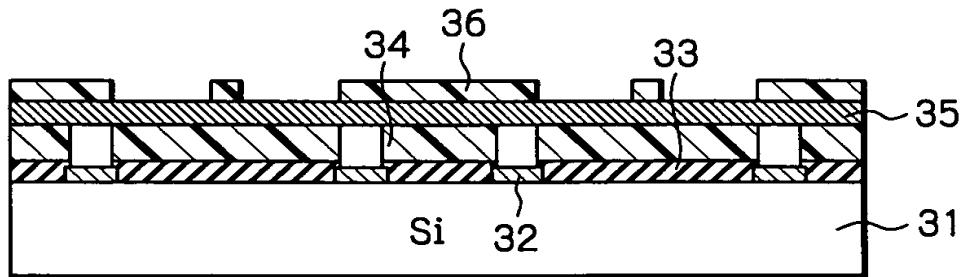


Fig. 8H

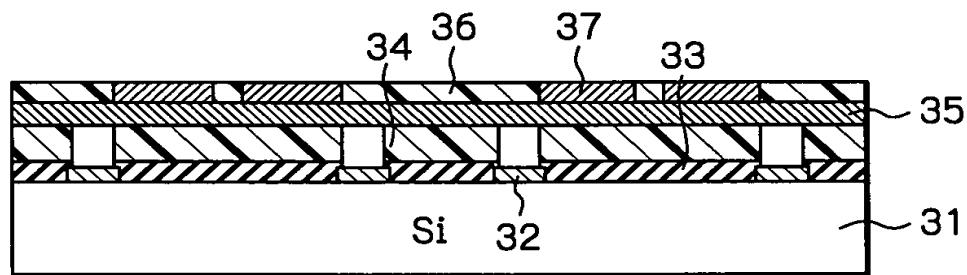
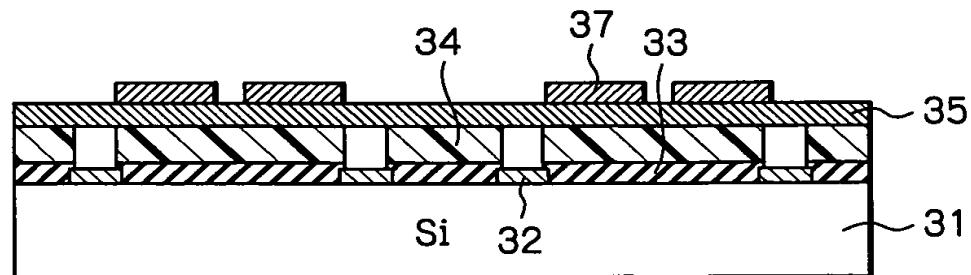


Fig. 8I



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Fig. 8J

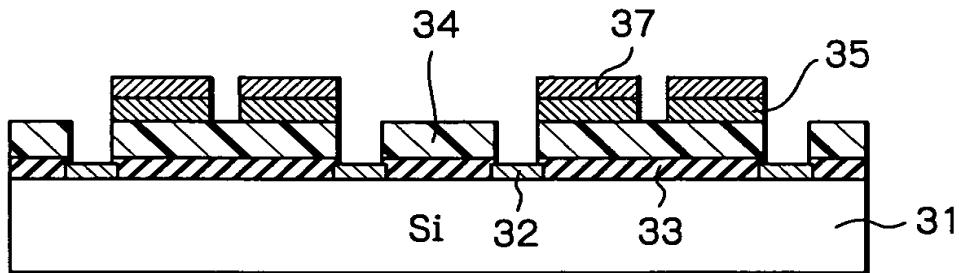


Fig. 8K

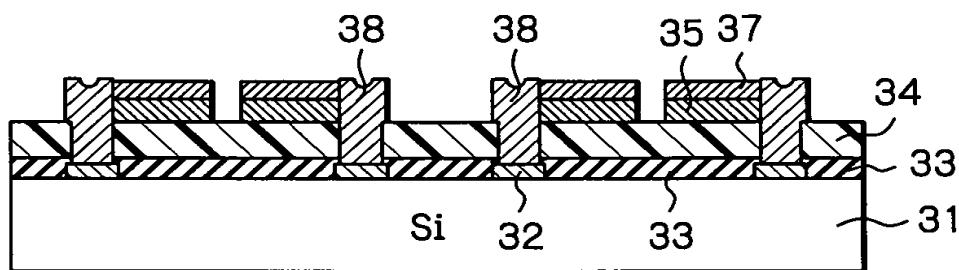
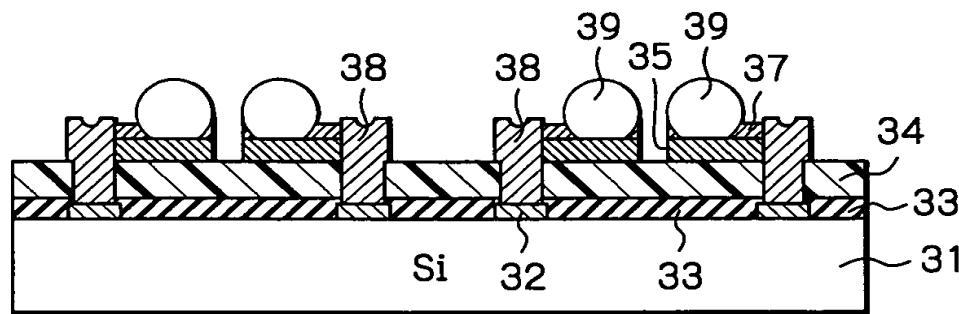


Fig. 8L



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Fig. 8M

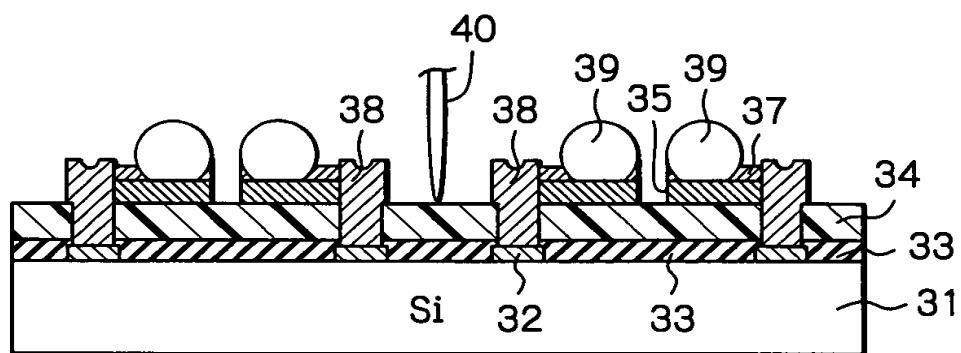


Fig. 8N

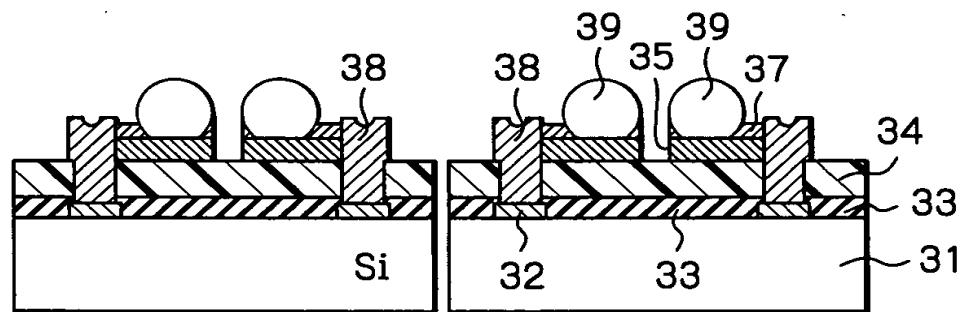


Fig. 9A

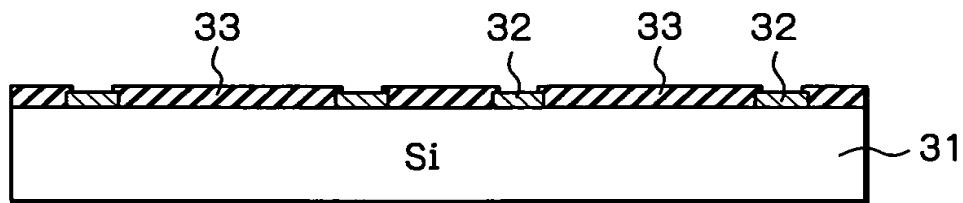


Fig. 9B

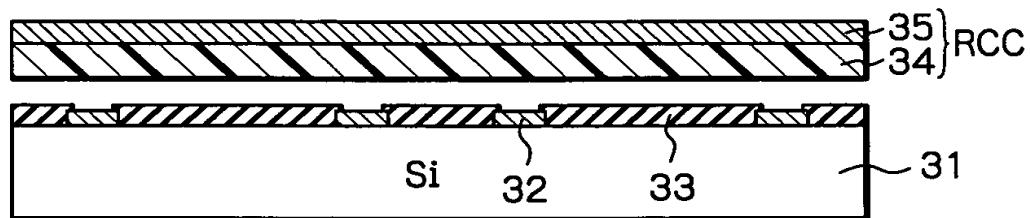


Fig. 9C

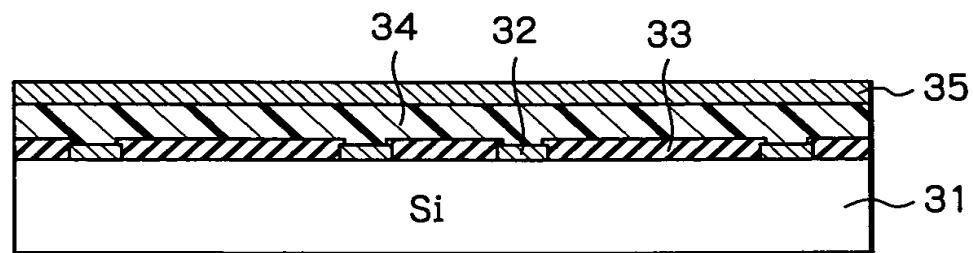


Fig. 10A

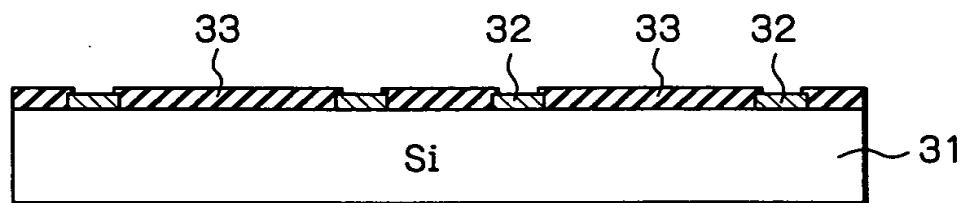


Fig. 10B

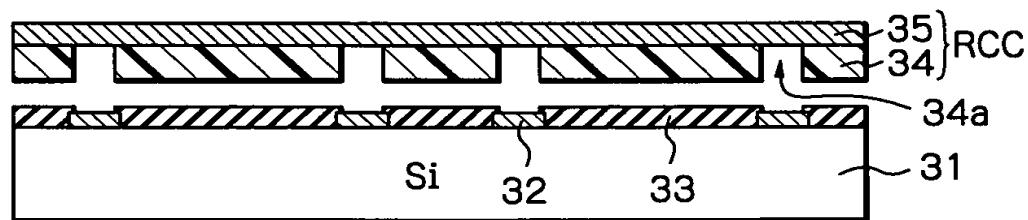
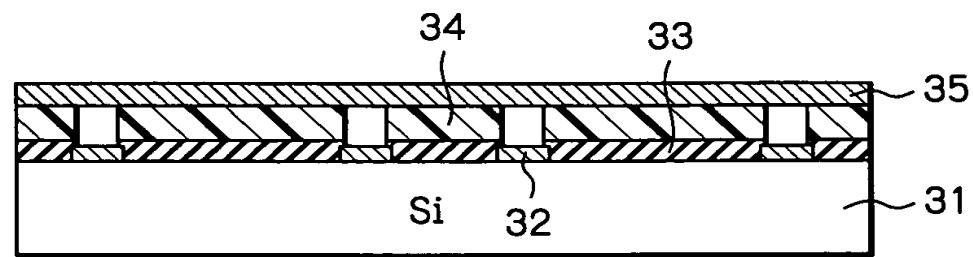


Fig. 10C



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Fig. 11A

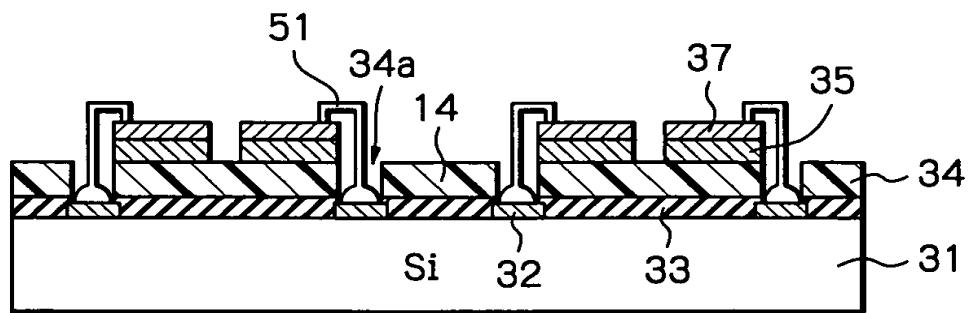


Fig. 11B

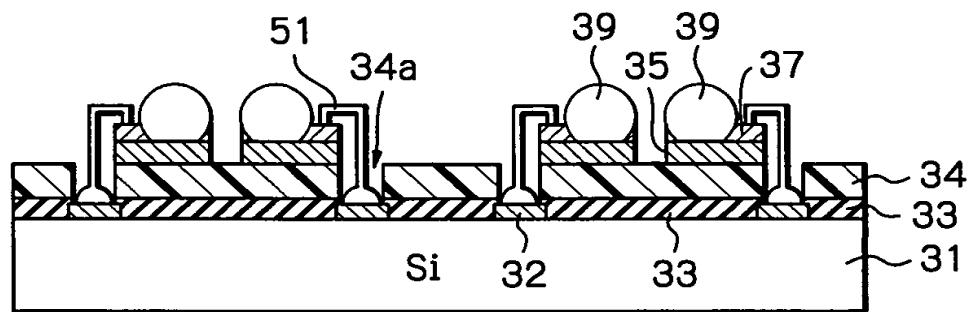


Fig. 11C

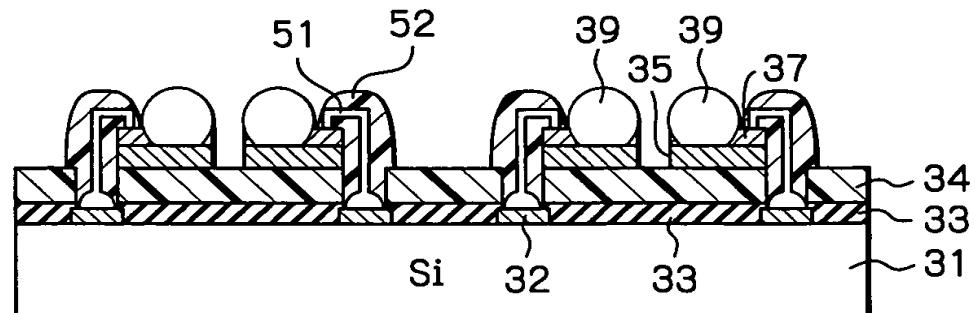


Fig. 11D

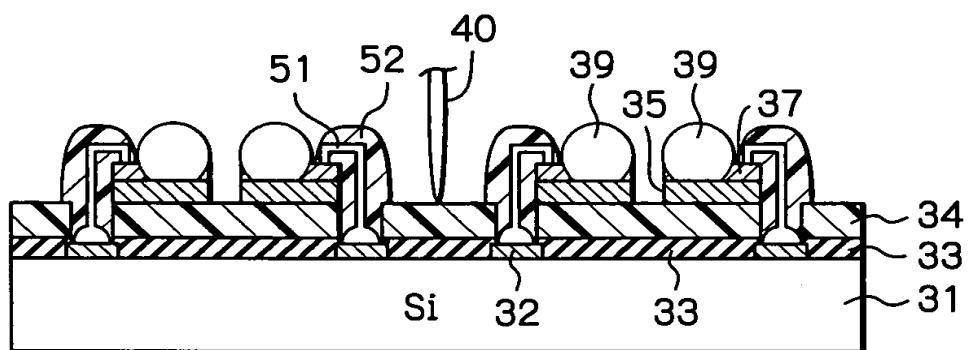
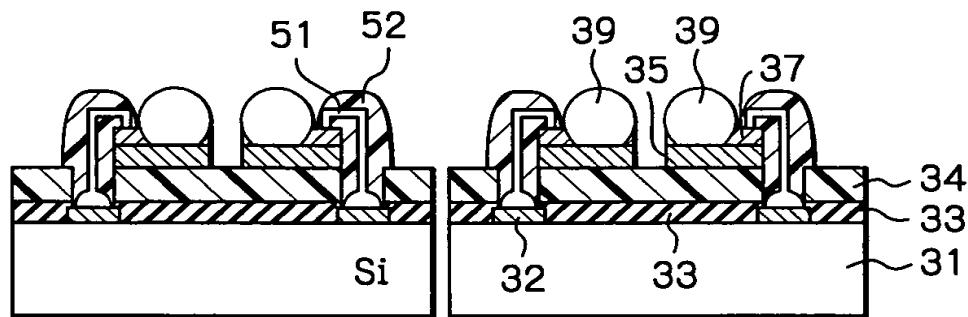


Fig. 11E



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Fig. 12A

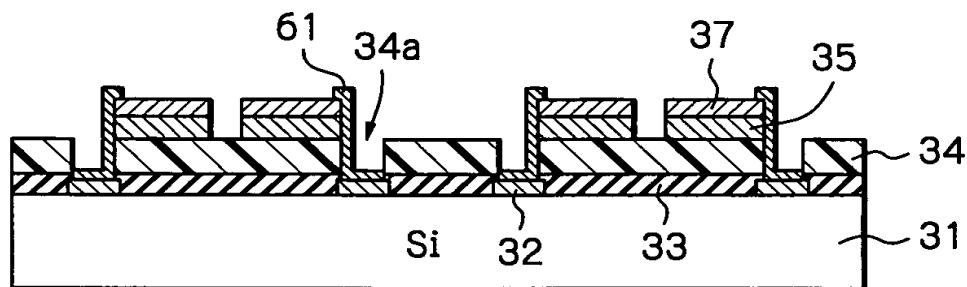


Fig. 12B

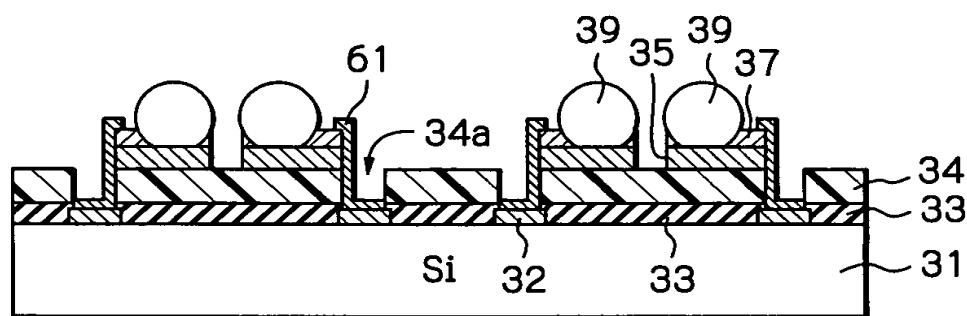
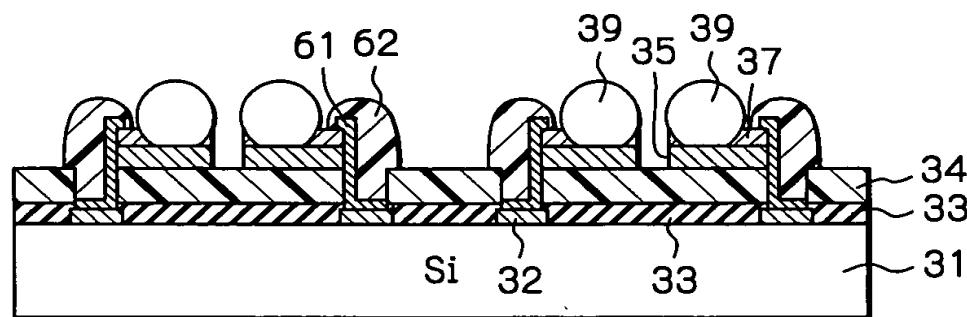


Fig. 12C



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Fig. 12D

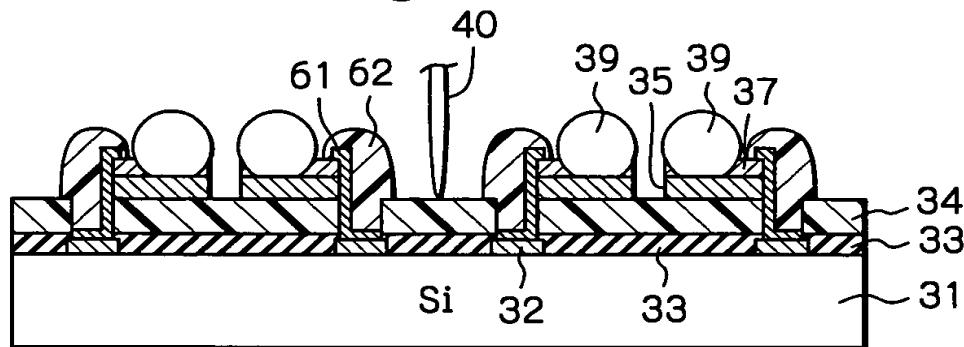
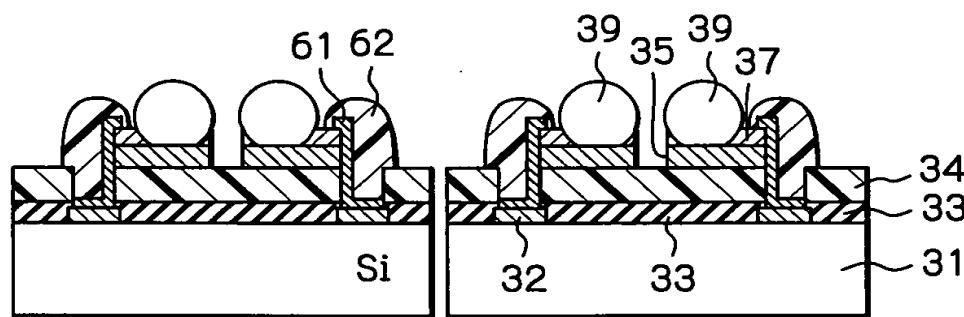


Fig. 12E



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Fig. 13A

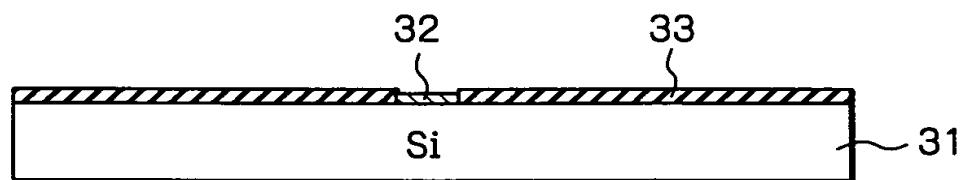


Fig. 13B

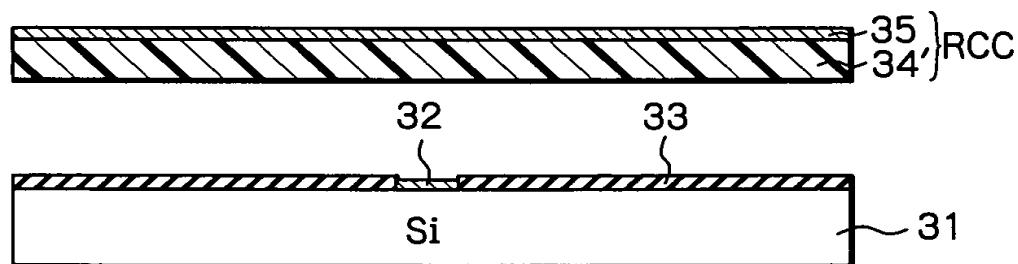
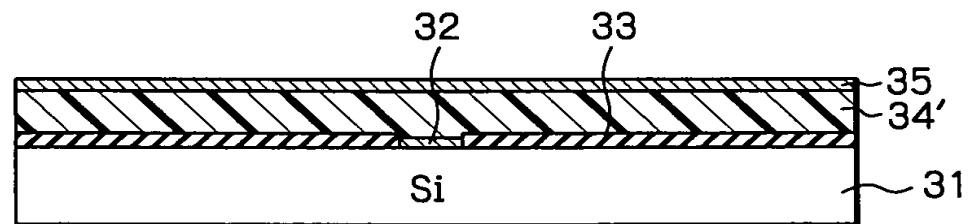


Fig. 13C



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Fig. 13D

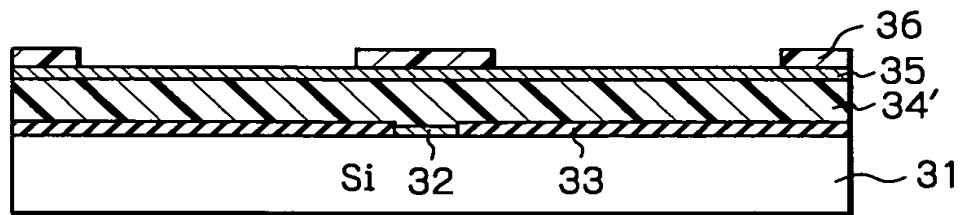


Fig. 13E

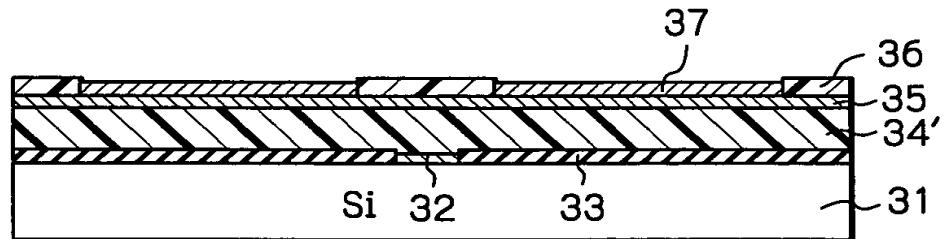
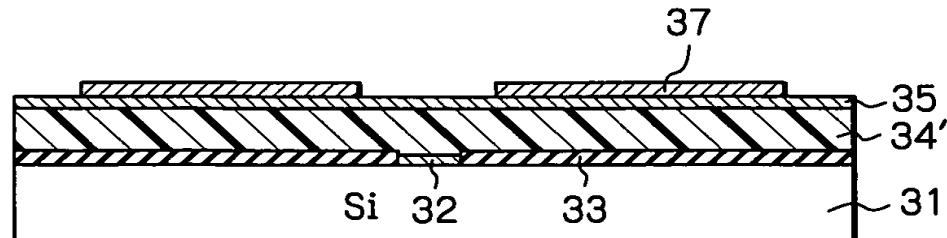


Fig. 13F



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Fig. 13G

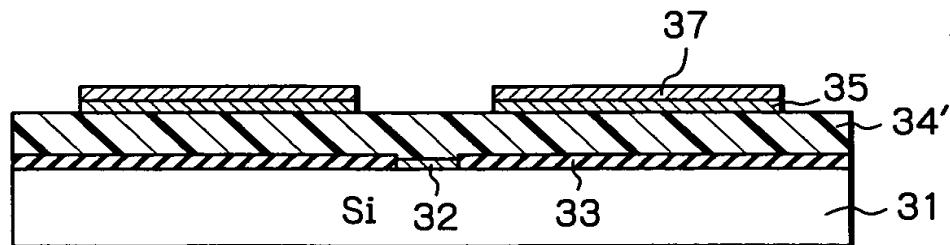


Fig. 13H

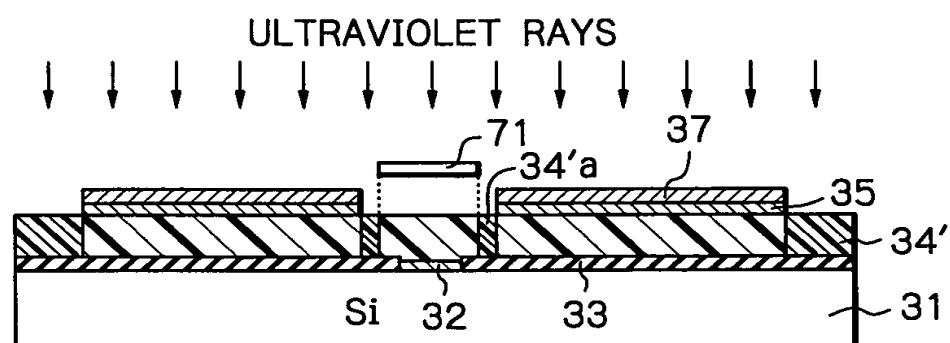
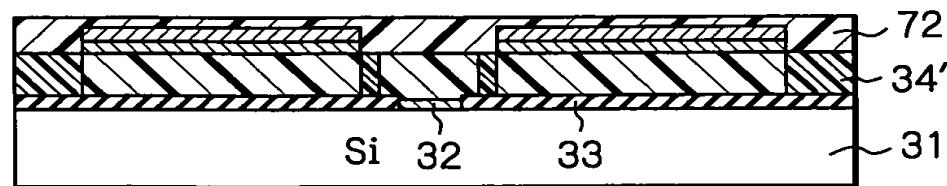


Fig. 13I



Title: METHOD OF MANUFACTURING A
FLIP-CHIP SEMICONDUCTOR DEVICE
WITH A STRESS-ABSORBING LAYER
MADE OF THERMOSETTING RESIN

Inventor(s): Hirokazu HONDA
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Fig. 13J

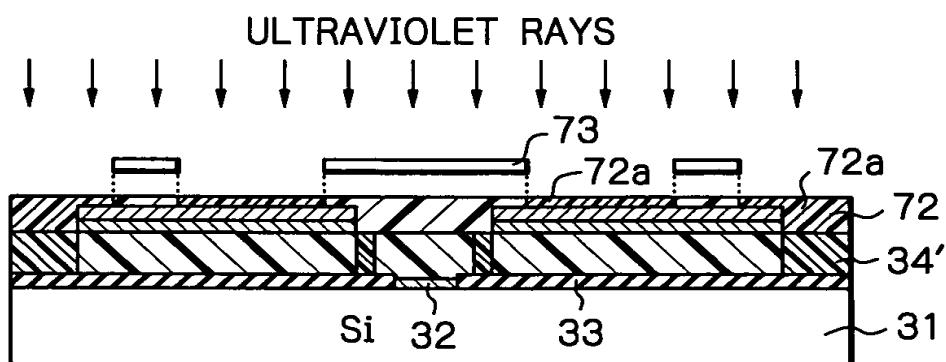
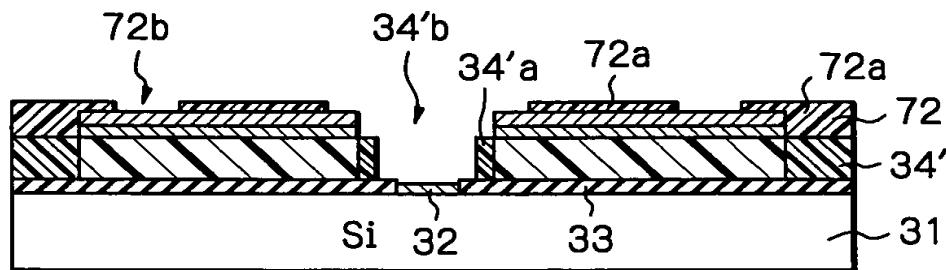


Fig. 13K



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Fig. 13L

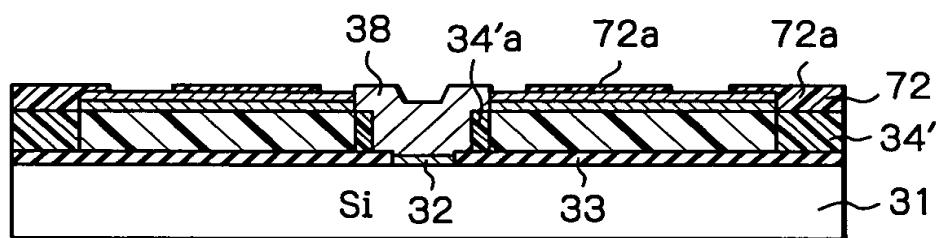
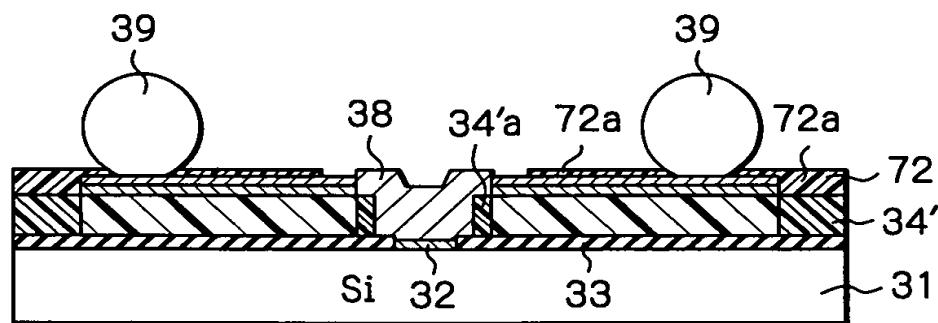


Fig. 13M



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Fig. 14A

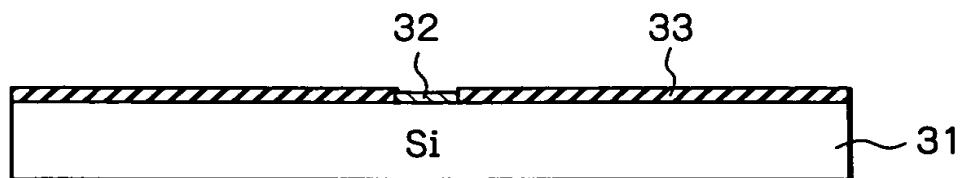


Fig. 14B

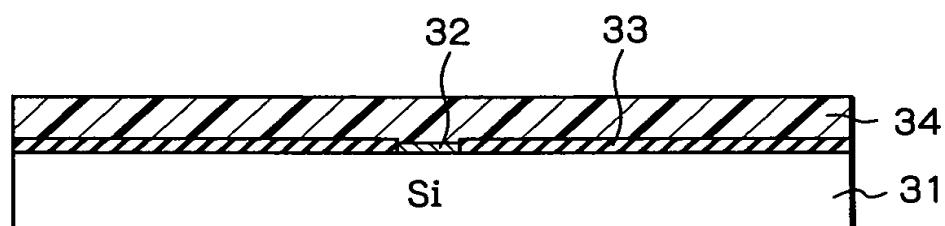
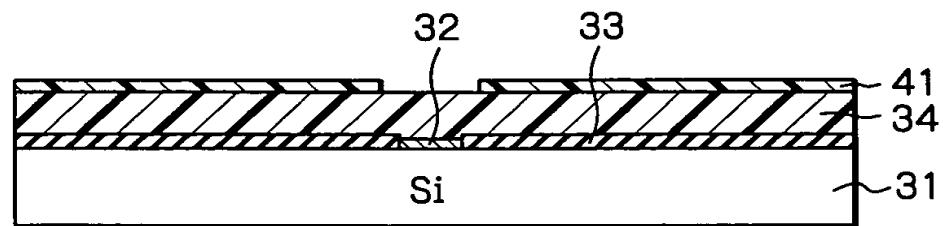


Fig. 14C



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Fig. 14D

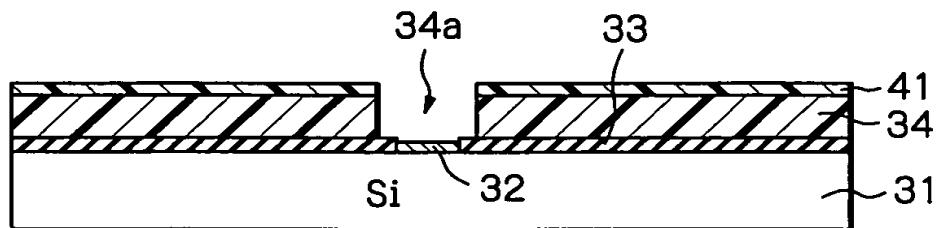


Fig. 14E

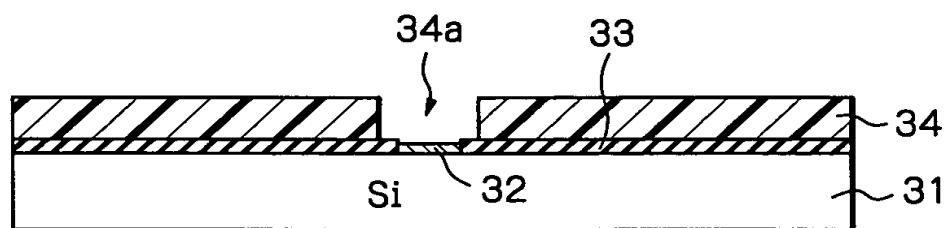
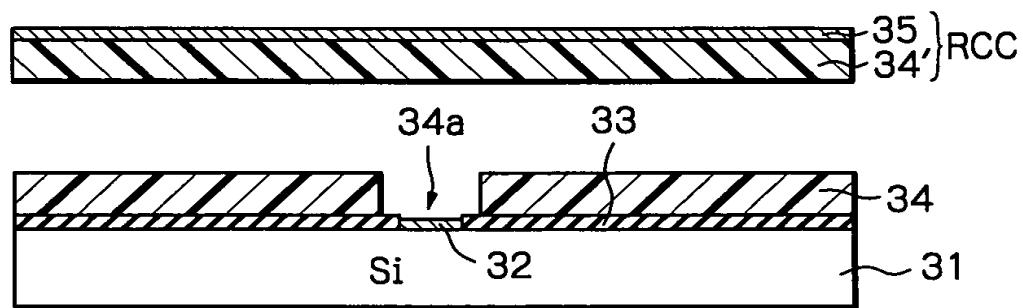


Fig. 14F



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Fig. 14G

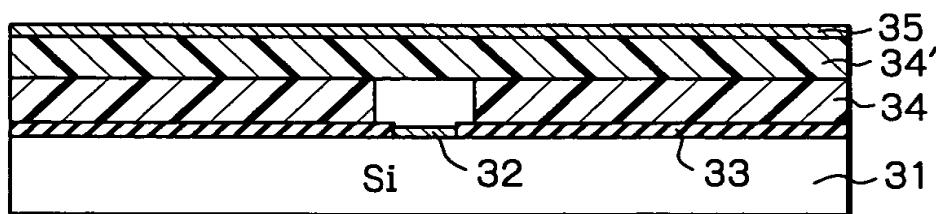


Fig. 14H

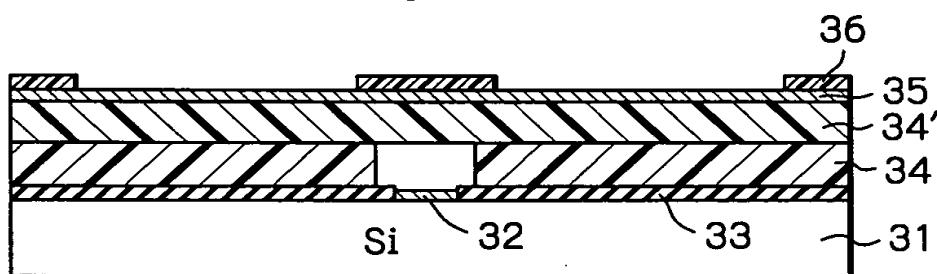


Fig. 14I

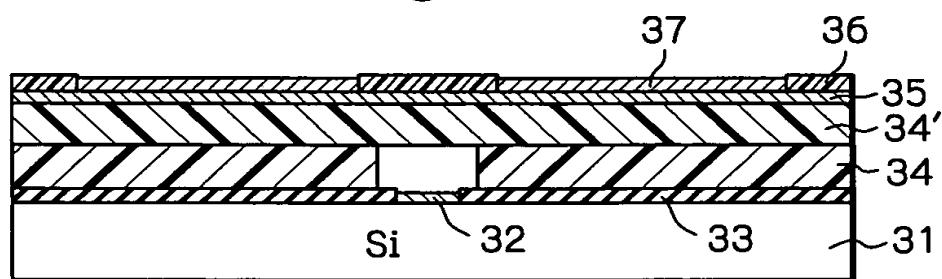


Fig. 14J

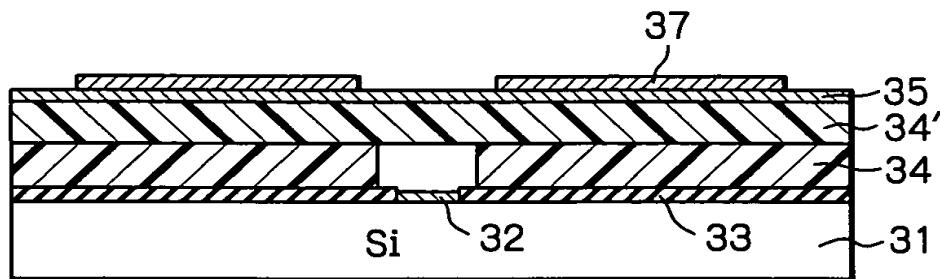


Fig. 14K

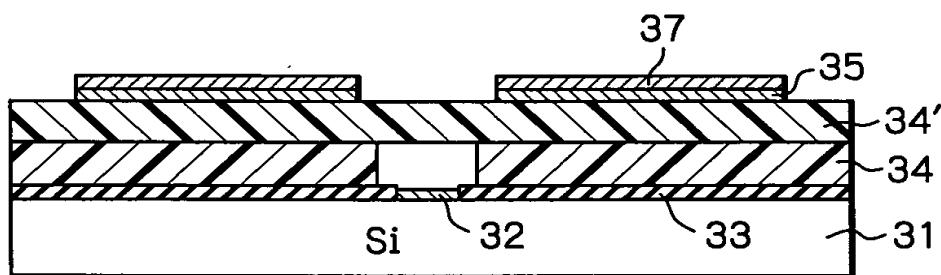


Fig. 14L

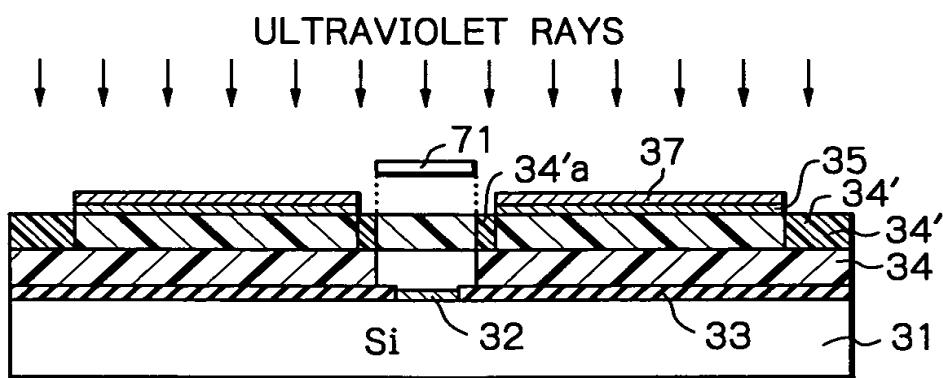


Fig. 14M

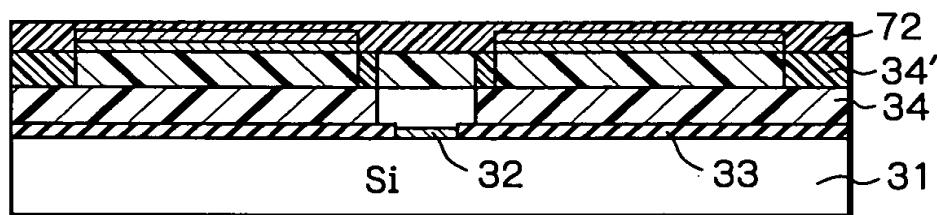


Fig. 14N

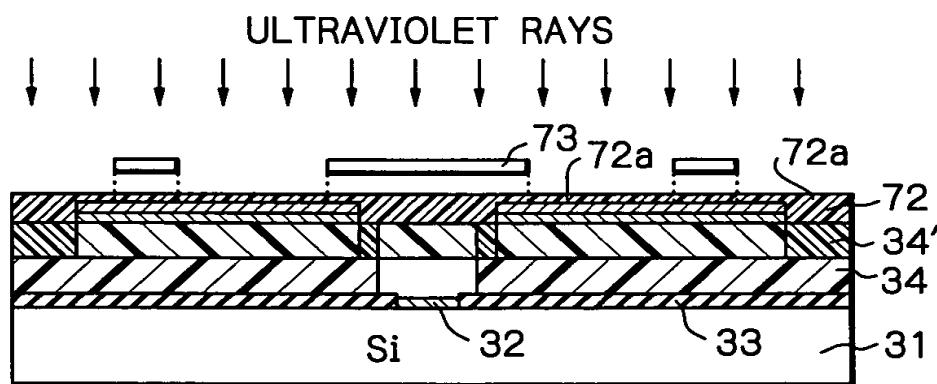
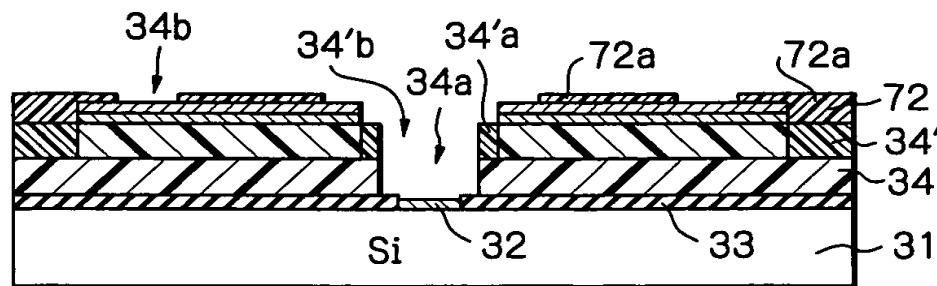


Fig. 14O



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Fig. 14P

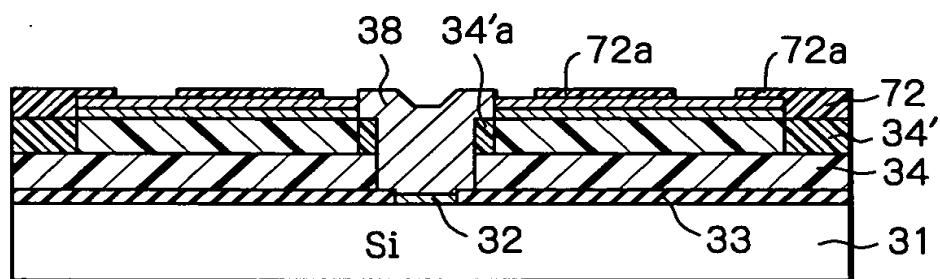


Fig. 14Q

